



Copper Bump Developer

High Capacity Manufacturing

Benefits

- High capacity heat exchanger allows process solution to maintain constant temperature
- Customer specific spray nozzles address the different requirements for spray patterns often required for dry films
- Stepping motor controlled raster arm achieves superior center to edge uniformity
- Proven software platform

Features

- Process 50 mm – 200 mm wafers
- PC Windows-based operating system with smartPro GUI
- Barcode and recipe download capable
- High performance motors for improved uniformity and reliability
- Component exercise mode
- CE Mark

System Options

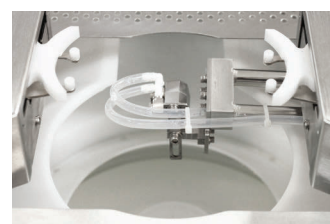
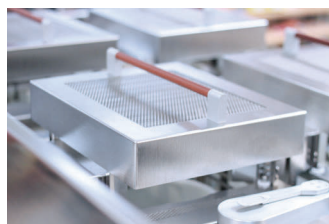
- SECS/GEM compliance
- Contact C&D for options

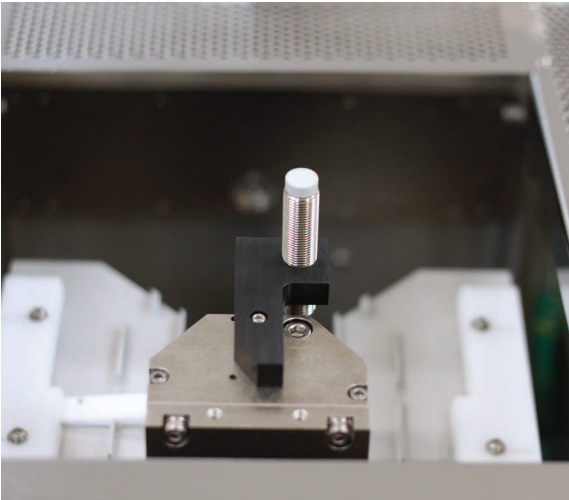
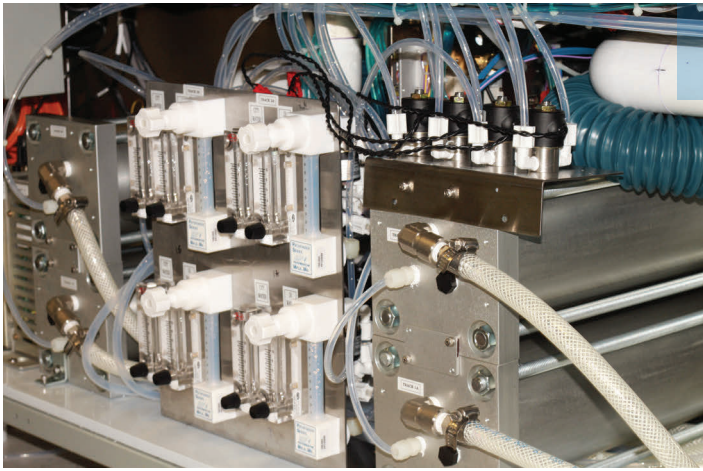
Description

The C&D Copper Bump Developer is designed specifically for developing dry laminated film resist. The high capacity heat exchanger allows process solution temperature to remain constant $\pm 2.0^{\circ}\text{C}$ and achieve up to 40°C for long constant spray develop cycles often required by thick laminated films. The heat exchanger can control the developer temperature to four process modules simultaneously for maximum flexibility and throughput. C&D's pressure tanks can interface with a bulk delivery system that dilutes the developer from a concentrate. This dilution system mixes and fills the canisters without track interruption saving time and money.



P8000 Copper Bump





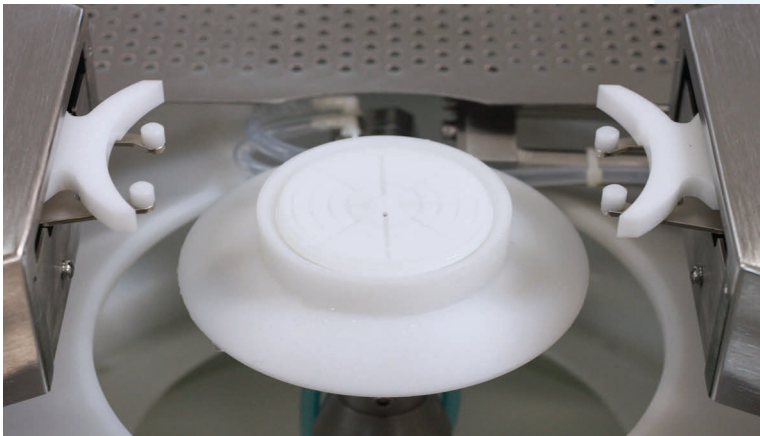
Proven software platform

C&D's proven software platform is a perfect fit for the Copper Bump process. The component exercise mode allows the user to optimize and to test spray patterns, supply pressure, and developer flow.

High capacity manufacturing

The Copper Bump Developer is capable of high capacity manufacturing.

With four process modules able to run simultaneously, the system throughput is maximized. C&D offers a variety of spray nozzles to choose from for customer specific spray fan patterns often required for dry films. The developer flow rate and pressure are fully adjustable.



Proven method for copper bump process

The high performance spindle motor along with customer specific spray nozzles, stepping motor controlled raster arm, and constant flow and temperature control of developer all optimize CD control. The raster arm movement capability is a proven method for the copper bump process. The digital high performance stepper motor is key to achieving center to edge uniformity.

Technical Data

Available modules	Copper bump developer
Wafer size	50 mm - 200 mm wafers
Transfer Method	Automatic transfer arm with improved design maintaining end-point placement to within ± 0.1 mm over 300,000 wafers.
Transfer Mode	Serial transport
User Interface	Windows-based operating system with smartPro GUI